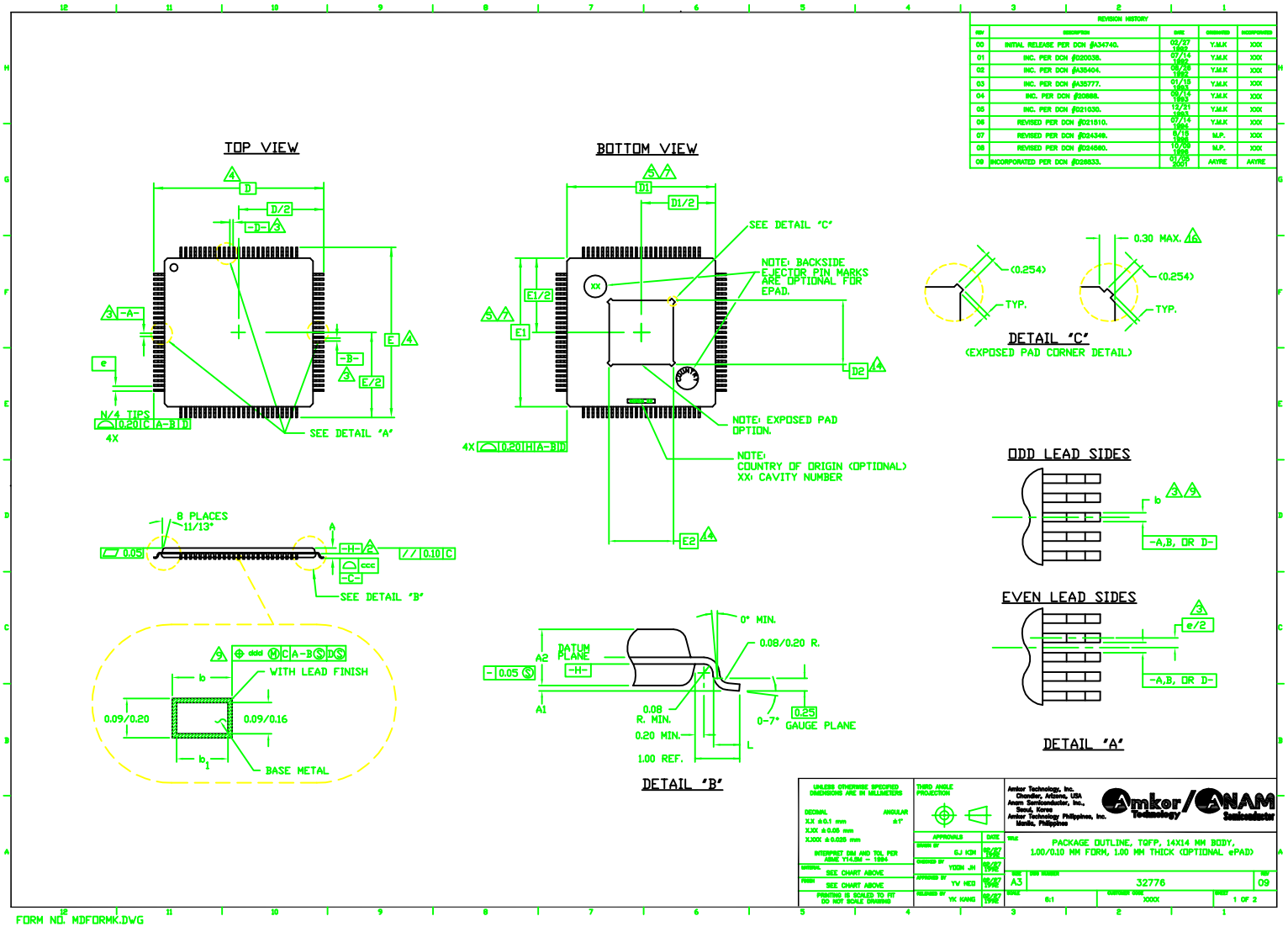
REVISION HISTORY
REV | DESCRIPTION | DATE | ORIGINATED | INCORPORATED
00 | INITIAL RELEASE PER DCN #A34740. | 02/97 1997 | Y.M.K | XXX
01 | INC. PER DCN #D20038. | 07/14 1998 | Y.M.K | XXX
02 | INC. PER DCN #A38404. | 01/28 1999 | Y.M.K | XXX
03 | INC. PER DCN #A35777. | 01/18 1999 | Y.M.K | XXX
04 | INC. PER DCN #20888. | 07/14 1999 | Y.M.K | XXX
05 | INC. PER DCN #021030. | 12/21 1999 | Y.M.K | XXX
06 | REVISED PER DCN #021510. | 07/14 1999 | Y.M.K | XXX
07 | REVISED PER DCN #024349. | 9/15 1999 | M.P. | XXX
08 | REVISED PER DCN #024580. | 10/05 1999 | M.P. | XXX
09 | INCORPORATED PER DCN #028833. | 01/05 2001 | AAYRE | AAYRE
TOP VIEW
BOTTOM VIEW
SEE DETAIL "C"
NOTE: BACKSIDE EJECTOR PIN MARKS ARE OPTIONAL FOR EPAD.
NOTE: EXPOSED PAD OPTION.
NOTE: COUNTRY OF ORIGIN (OPTIONAL) XX: CAVITY NUMBER
SEE DETAIL "A"
SEE DETAIL "B"
4X N/4 TIPS
4X
8 PLACES 11/13°
WITH LEAD FINISH
BASE METAL
0.09/0.20
0.09/0.16
DETAIL "B"
DETAIL "C"
(EXPOSED PAD CORNER DETAIL)
0.30 MAX.
(0.254)
TYP.
ODD LEAD SIDES
EVEN LEAD SIDES
-A,B, OR D-
DETAIL "A"
0° MIN.
0.08/0.20 R.
0.08 R. MIN.
0.20 MIN.
1.00 REF.
0-7°
0.25 GAUGE PLANE
DATUM PLANE
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS
DECIMAL X.X ±0.1 mm X.XX ±0.05 mm X.XXX ±0.025 mm
ANGULAR ±1°
INTERPRET DIM AND TOL PER ASME Y14.5M – 1994
FINISH SEE CHART ABOVE
MATERIAL SEE CHART ABOVE
DRAWING IS SCALED TO FIT DO NOT SCALE DRAWING
THIRD ANGLE PROJECTION
APPROVALS | DATE
DRAWN BY GJ KIM 10/27/1999
CHECKED BY YOON JH 10/27/1999
APPROVED BY YV HEO 10/27/1999
RELEASED BY YK KANG 10/27/1999
Amkor Technology, Inc. Chandler, Arizona, USA
Anam Semiconductor, Inc., Seoul, Korea
Amkor Technology Philippines, Inc. Manila, Philippines
Amkor/ANAM Semiconductor
TITLE: PACKAGE OUTLINE, TQFP, 14X14 MM BODY, 1.00/0.10 MM FORM, 1.00 MM THICK (OPTIONAL ePAD)
SIZE A3 | DWG NUMBER 32776 | REV 09
SCALE 0:1 | CONTRACT NUMBER XXXX | SHEET 1 OF 2
FORM NO. MDFORMK.DWG